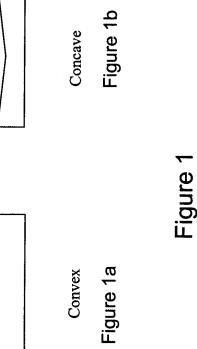
Attorney's Docket No.: 111079-136359 Page 1 of 4
First Named Inventor: Yew Wee Cheong Application No.: Not Yet Assigned
Title: LOW-K INTERLAYER DIELECTRIC WAFER GRINDING
Express Mail Label No. ER084884074US Date of Deposit: 03/30/2004



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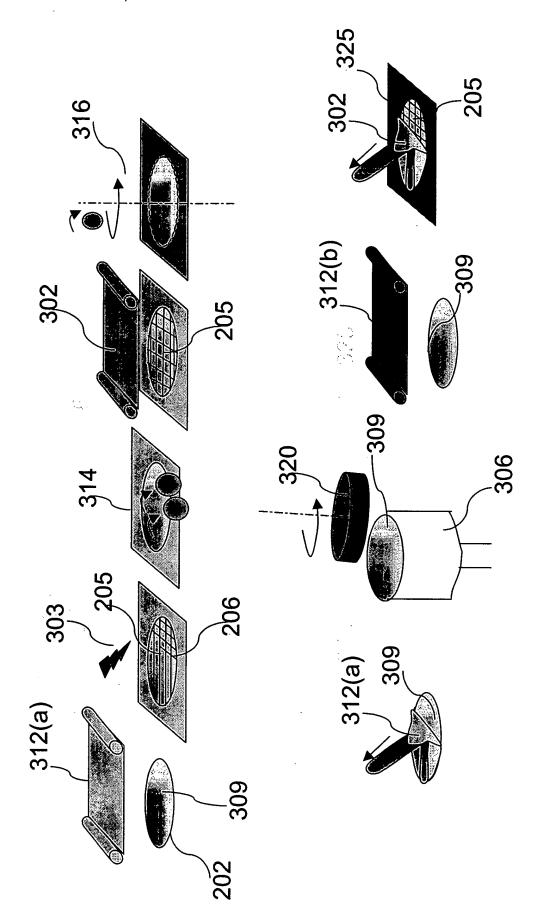


Figure 3

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